



**THE DATASHEET OF
ERB-SE0R75U**



To Digi Key

Micro Chip Fuse
ERBSE type

Reliability test Data

Panasonic Electronic Devices Co., Ltd
Circuit Components Business Unit

Contents

1. Resistance to Soldering Heat
2. Temperature Cycle
3. Vibration
4. Endurance (Under Load and Heat)
5. Endurance (Under Load and Damp)
6. Resistance to Damp
7. Resistance to Solvent
8. Resistance to Heat
9. Resistance to Cold
10. Reference data (Fusing Characteristics)

Panasonic

1. Resistance to Soldering Heat

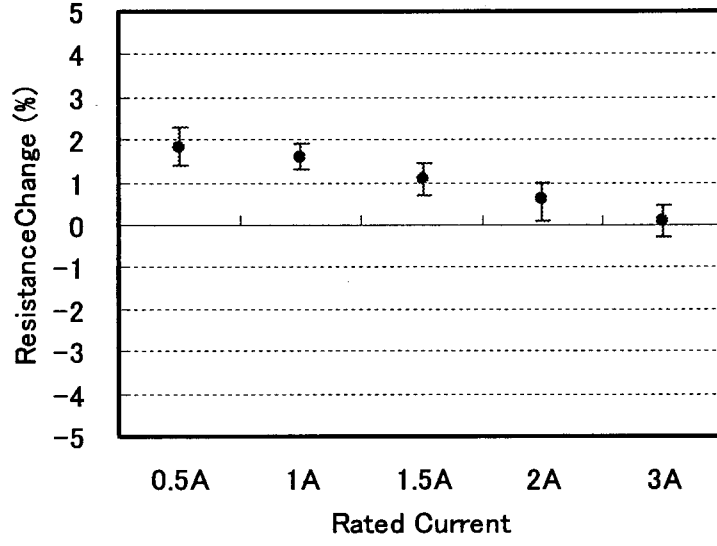
Method: Reflow peak temperature: 260 deg.C, time: 10s

Criteria and Result: Resistance change $< \pm 10\%$,

100% of rated current at 25 deg.C : No open for 4 hours minimum

200% of rated current at 25 deg.C. : Open within 5 seconds maximum

n=12



2. Temperature Cycle

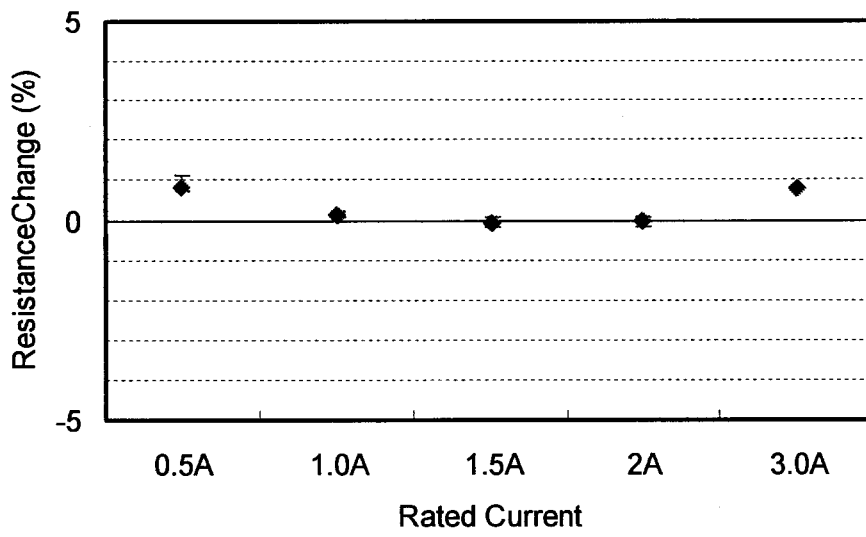
Method: -40 to +100 deg.C (each 30 minutes), 5 cycles

Criteria and Result: Resistance change $< \pm 10\%$,

100% of rated current at 25 deg.C : No open for 4 hours minimum

200% of rated current at 25 deg.C. : Open within 5 seconds maximum

n=24



Panasonic

3. Vibration

Method: Testing frequency: 10 to 55 to 10 Hz (sweep time 1 minutes),

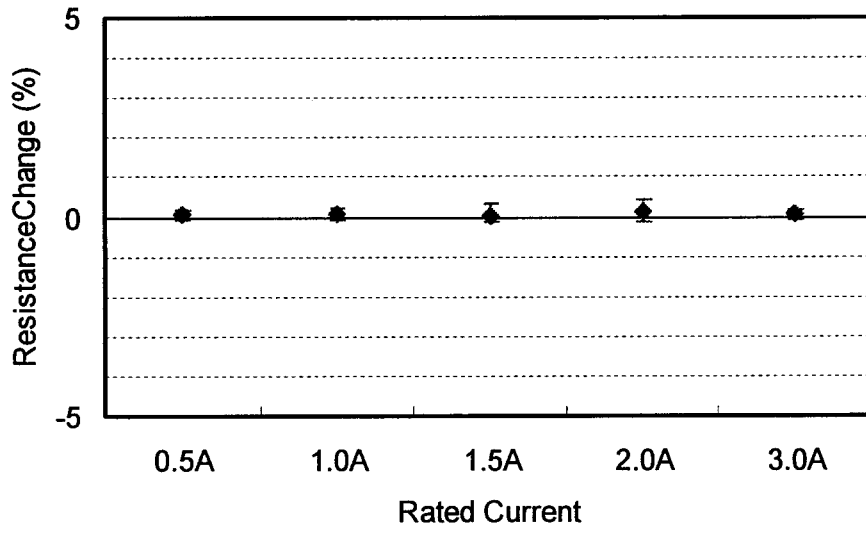
All the amplitude: 1.5 mm, 3(X,Y,Z) directions each 2 hours.

Criteria and Result: Resistance change $< \pm 10\%$,

100% of rated current at 25 deg.C : No open for 4 hours minimum

200% of rated current at 25 deg.C. : Open within 5 seconds maximum

n=24



Panasonic

4. Endurance (Under Load and Heat)

Method: Temp.: 70 +/-2 deg.C ,

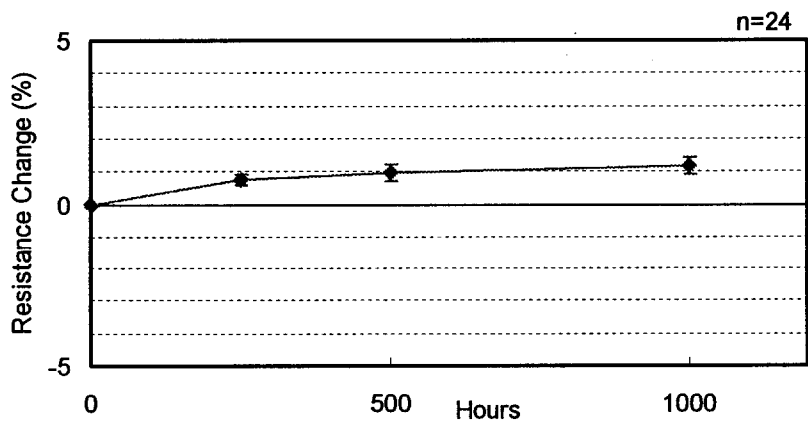
Load: 70% rated current/1.5 hours ON and 0.5 hours OFF/1000 hours.

Criteria and Result: Resistance change <+/-10%,

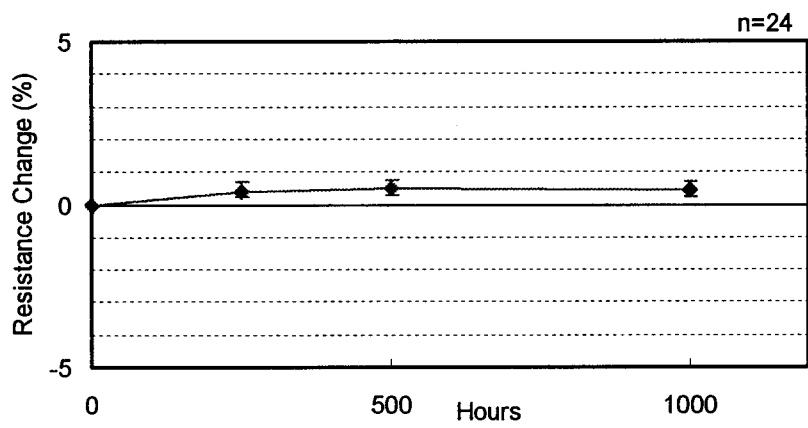
100% of rated current at 25 deg.C : No open for 4 hours minimum

200% of rated current at 25 deg.C. : Open within 5 seconds maximum

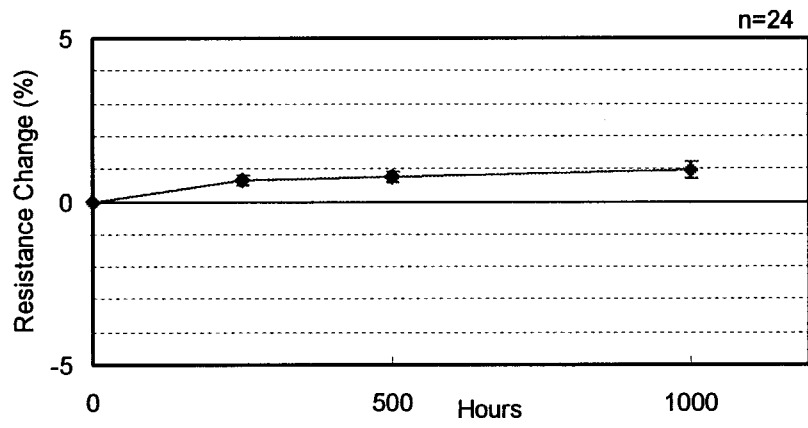
ERBSE0R50



ERBSE1R50



ERBSE3R00



Panasonic

5. Endurance (Under Load and Damp)

Method: Temp. and Humidity: 60 +/-2 deg.C and 90 to 95% RH,

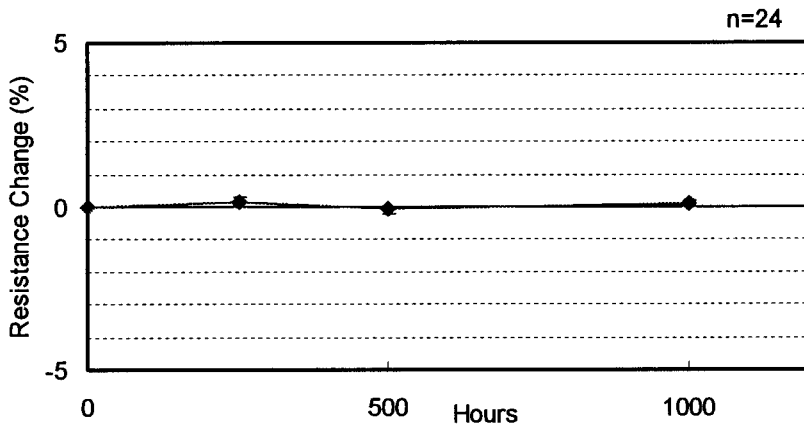
Load: 70% rated current/1.5 hours ON and 0.5 hours OFF/1000 hours.

Criteria and Result: Resistance change <+/-10%,

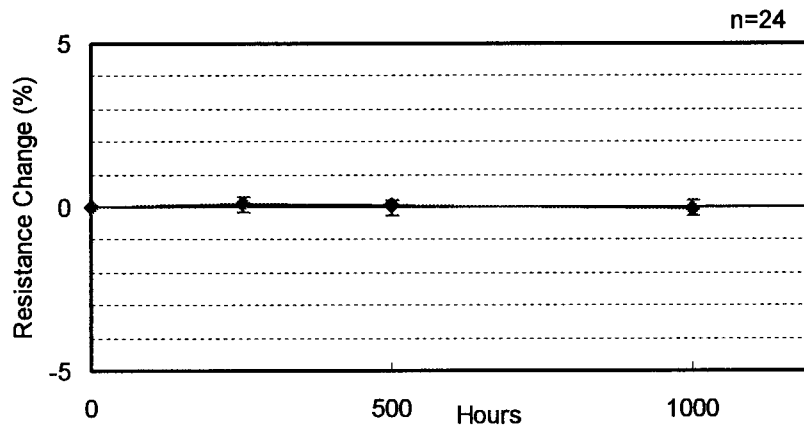
100% of rated current at 25 deg.C : No open for 4 hours minimum

200% of rated current at 25 deg.C. : Open within 5 seconds maximum

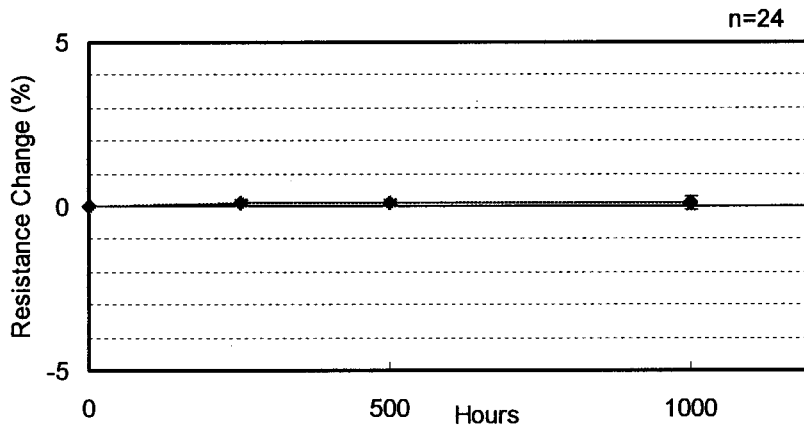
ERBSE0R50



ERBSE1R50



ERBSE3R00



Panasonic

6. Resistance to Damp

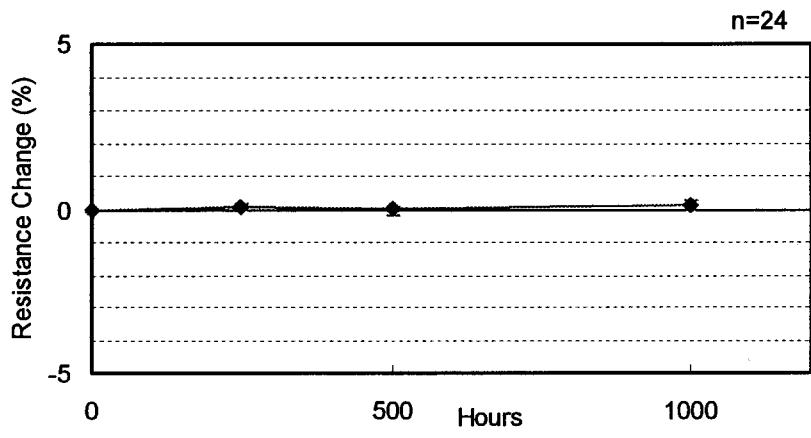
Method: Temp. and Humidity: 60 +/-2 deg.C and 90 to 95% RH/1000 hours (no load).

Criteria and Result: Resistance change <+/-10%,

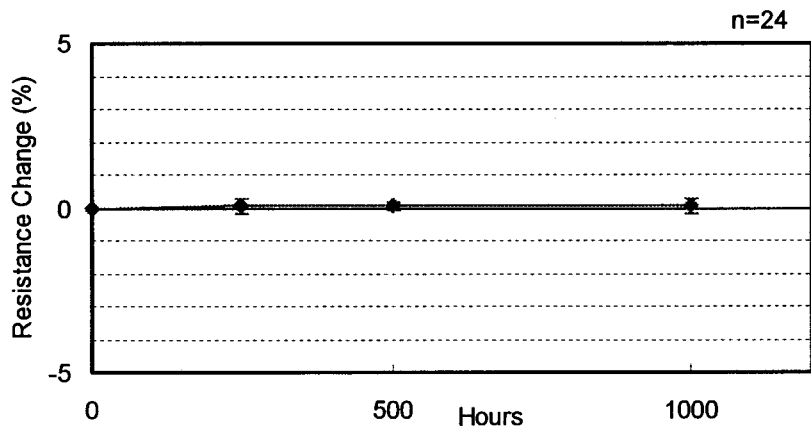
100% of rated current at 25 deg.C : No open for 4 hours minimum

200% of rated current at 25 deg.C : Open within 5 seconds maximum

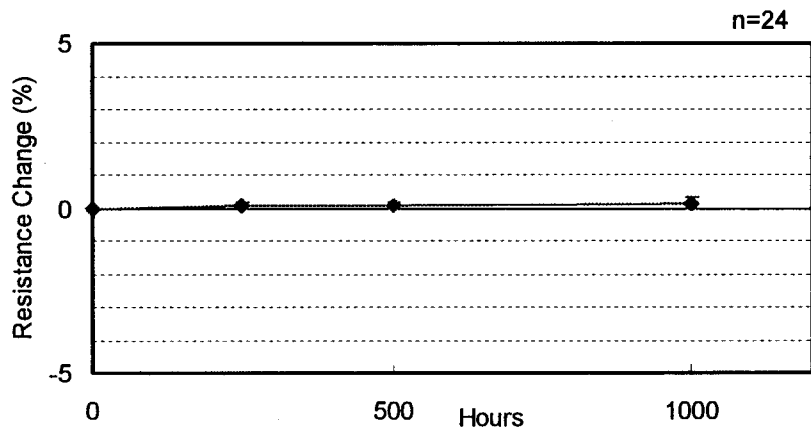
ERBSE0R50



ERBSE1R50



ERBSE3R00



Panasonic

7. Resistance to Solvent

Method: Appearance after dipping into 2-propanol(IPA)/10 minutes.

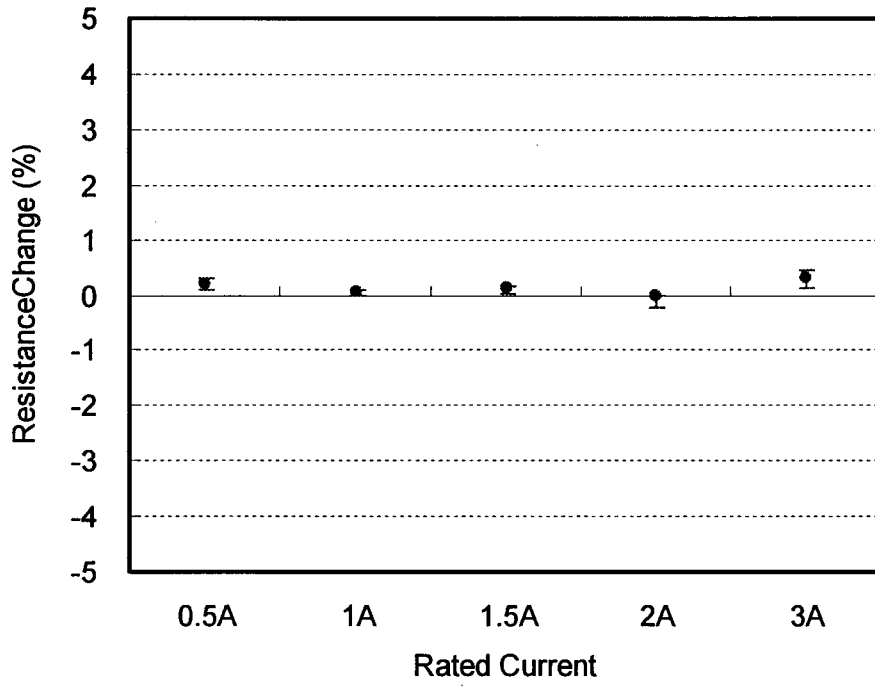
Criteria and Result:

No abnormality on appearance, Resistance change <+/-10%,

100% of rated current at 25 deg.C : No open for 4 hours minimum

200% of rated current at 25 deg.C. : Open within 5 seconds maximum

n=12



Panasonic

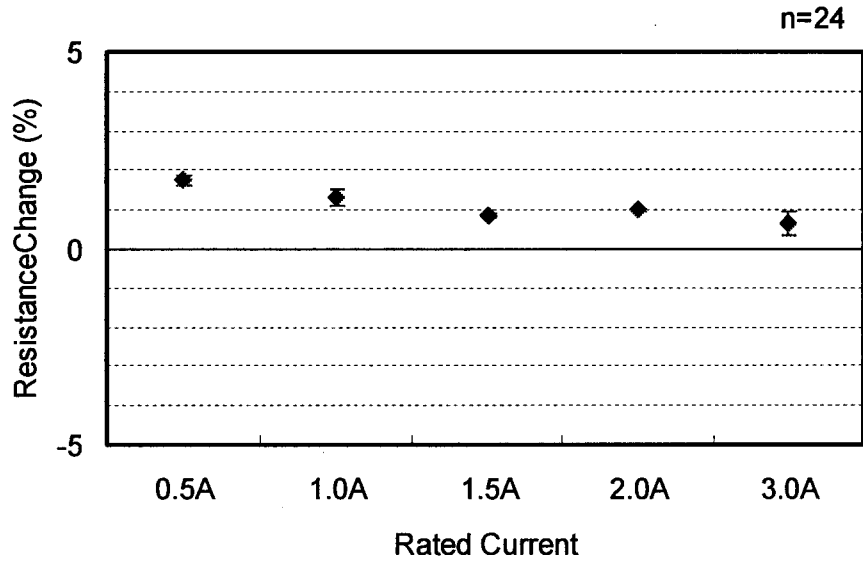
8. Resistance to Heat

Method: Temp.: +100 +/-2 deg.C ,

Criteria and Result: Resistance change <+/-10%,

100% of rated current at 25 deg.C : No open for 4 hours minimum

200% of rated current at 25 deg.C. : Open within 5 seconds maximum



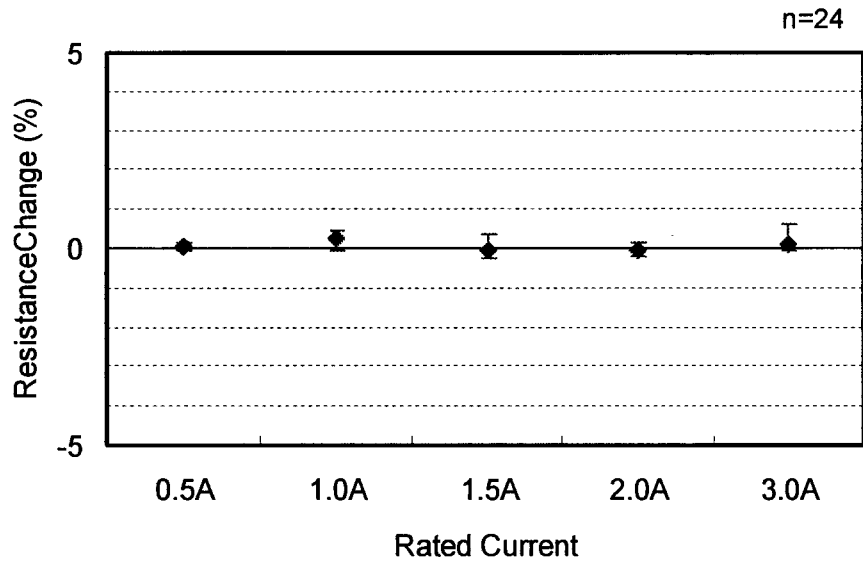
9. Resistance to Cold

Method: Temp.: -40 +/-2 deg.C ,

Criteria and Result: Resistance change <+/-10%,

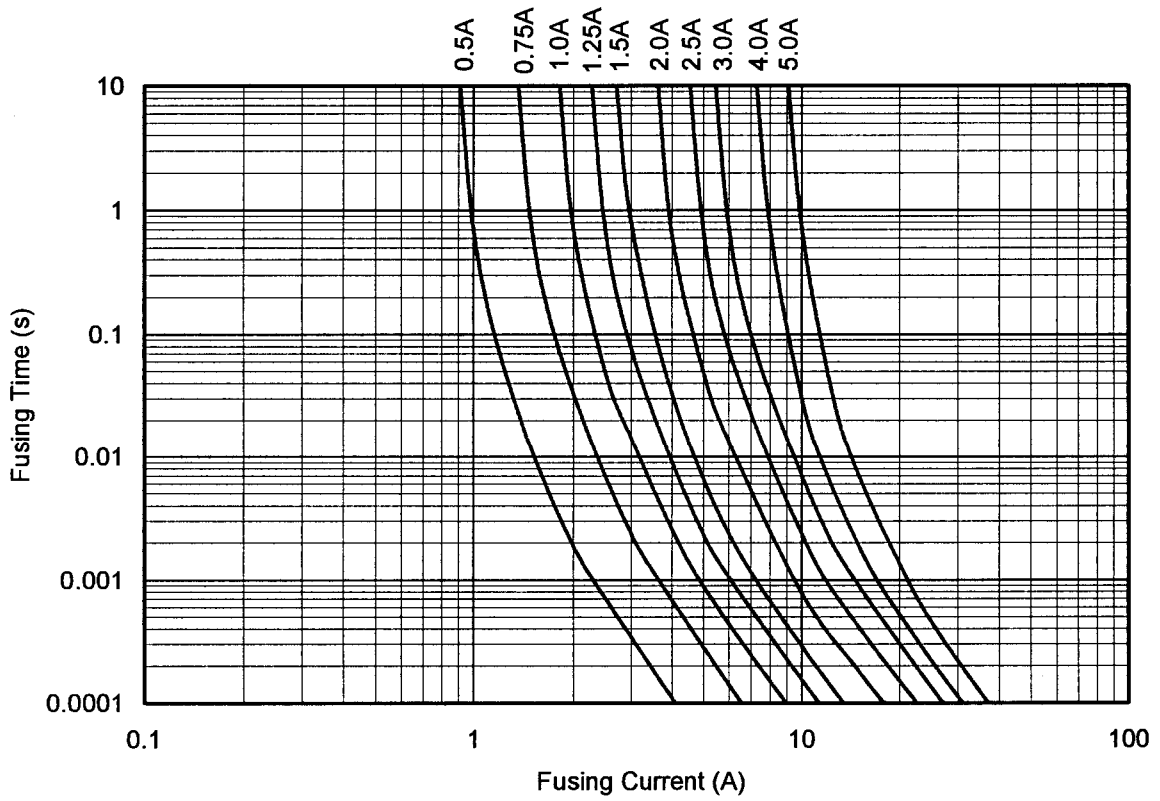
100% of rated current at 25 deg.C : No open for 4 hours minimum

200% of rated current at 25 deg.C. : Open within 5 seconds maximum

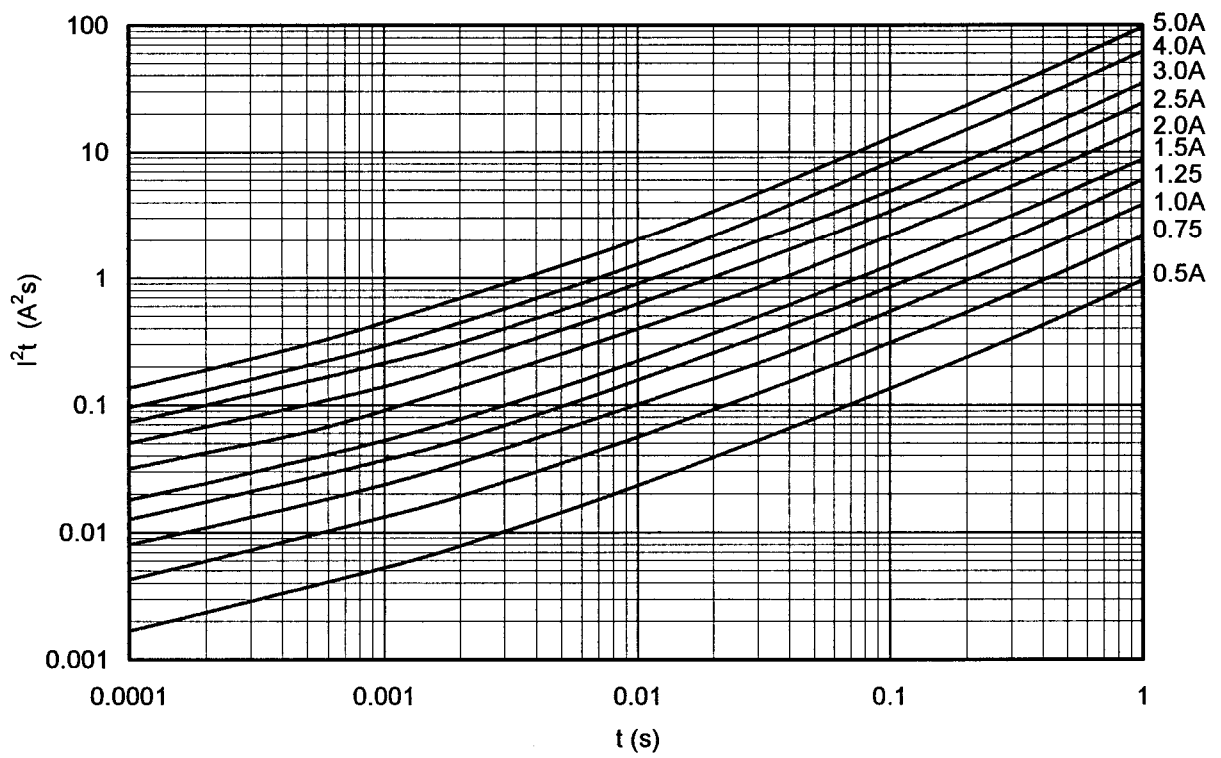


10. Reference data (Fusing Characteristics)

ERBSE series / I-t Characteristics (25°C, Typical)



ERBSE series / I²t Characteristics (25°C, Typical)









Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

 [View ERB-SE0R75U on WIN SOURCE](#)

 [Panasonic Information](#)

Optimize Your Supply Chain with WIN SOURCE Solutions

-  Global Sourcing Solution
-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management